

APPROVAL SHEET

承 认 书

记录编号： 版本： v0.3

| | |
|----------------------------------|---|
| Customer 客户名称 | |
| Part NO. 产品型号 | ZJY320IT008 |
| Product type 产品内容 | Mode: Transmissive type .Normally white. TFT LCD Module LCD Module: Graphic 240RGB*320Dot-matrix |
| Remarks 备注栏 | <input type="checkbox"/> APPROVAL FOR SEPCIFICATIONS ONLY <input checked="" type="checkbox"/> APPROVAL FOR SEPCIFICATIONS AND SAMPLE |
| Signature by Customer: 客户确认签章 | |

中景园确认

| | | |
|----|----|----|
| 核准 | 审核 | 定制 |
| | | |

客户确认

| | | |
|----|----|----|
| 核准 | 审核 | 审核 |
| | | |

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1.General Description

Z320IT008 is a 240RGB*320 dots matrix TFT LCD module. It has a TFT panel composed of 720 sources and 320gates. The LCM can be easily accessed by micro-controller.

2. Features

| | |
|-------------------|---|
| Display Mode | Transmissive |
| | a-TFT |
| Display Format | Graphic 320RGB*480 Dot-matrix |
| Input Data | 3 线串口/4 线串口/8 bits /16bits parallel interface |
| Viewing Direction | Wide viewing(宽视角) |
| Drive | ILI9341 |

3. Mechanical Specification

| Item | Specifications | Unit |
|---------------------|--|------|
| Dimensional outline | 54.00(W)*77.40 (H)*3.45+/-0.15(T) (FPC not include) | mm |
| Resolution | 240RGB*320 | dots |
| LCD Active area | 48.60(W)*64.80(H) | mm |
| Pixel size | 0.2025(W)*0.2025(H) | mm |

4. Mechanical Dimension

5. Maximum Ratings

| Item | Symbol | Min | Max | Unit | Note |
|-----------------------|------------------|------|----------------------|------|------|
| Supply voltage | V | -0.3 | 4.6 | V | |
| Operating temperature | V _T | -0.3 | V _{CC} +0.3 | V | |
| Storage temperature | T _{OPR} | -20 | 70 | °C | |
| Storage temperature | T _{STR} | -30 | 80 | °C | |

6. Electrical Characteristics

| Item | | Symbol | Condition | Min. | Typ. | Max. | Unit |
|---------------------|---------|-----------------|---|-----------|------|------------|------|
| Supply voltage | Logic | V _{CC} | | 2.7 | 2.8 | 3.3 | V |
| Input Voltage | H level | T _{IH} | | 0.8*IOVCC | | IOVCC | V |
| | L level | T _{IL} | | -0.3 | | 0.2* IOVCC | |
| Storage temperature | | I _{DD} | With internal voltage generation V _{CC} =2.8V; T _{emp} =25°C | | | TBD | mA |

7. Backlight Characteristic

| Item | Symbol | Min | Typical | Max | Unit |
|-----------------------------------|------------------|------|---------|-----|-------------------|
| LED module Forward voltage | V _{LED} | 3.0 | 3.2 | 3.4 | V |
| LED module current | V _{LED} | | 90 | | mA |
| L/G Surface Luminance ★1 | L _S | 3500 | | | Cd/m ³ |
| LCM Surface brightness uniform ★2 | L _D | 80 | | | % |

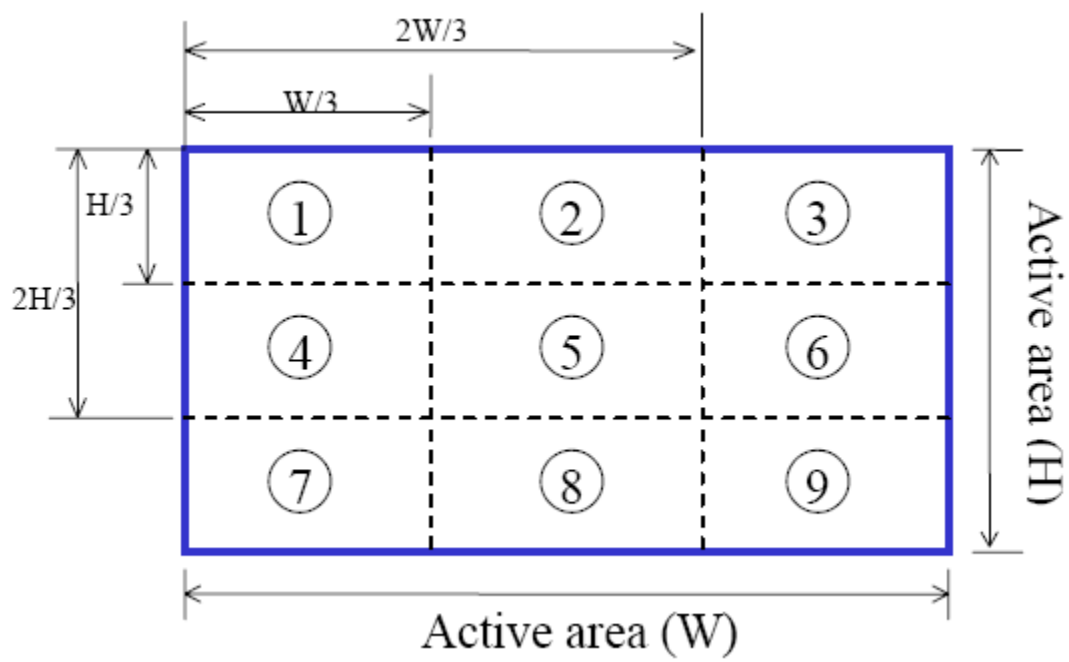
★ 1Test condition is:

- (a) Center point on active area.
- (b)Best Contrast.

★2Uniform measure condition:

- (1)Measure 9 point. Measure location show below;
- (2)Uniform=(Min. brightness /Max. brightness)*100%

(3)Best Contrast.



8. Module Function Description

8.1 Pin Descriptions

| PIN No. | Symbol | Description |
|---------|----------------|--|
| 1 | X(L) | Touch panel control pin (触摸屏控制脚) |
| 2 | Y(U) | Touch panel control pin (触摸屏控制脚) |
| 3 | X(R) | Touch panel control pin (触摸屏控制脚) |
| 4 | Y(D) | Touch panel control pin (触摸屏控制脚) |
| 5 | GND | Ground (接地脚) |
| 6 | I0VCC | Power supply for LCM (2.8V-3.3V) (屏供电脚) |
| 7 | VCI | Power supply for LCM (2.8V-3.3V) (屏供电脚) |
| 8 | FMARK | Tearing effect output pin to synchronize MPU to frame writing, activated by S/W command. When this pin is not activated, this pin is low. If not used, open this pin. (帧同步信号, 不用时悬空) |
| 9 | CS/SPI CS | Chip select pin ("Low" enable) (屏驱动芯片片选脚, 低电平有效) |
| 10 | RS/SPI SCL/SCK | This pin is used to select "Data or Command" in the parallel interface or serial data interface. (用于并口或者串口) Parallel(并口): When RS= '1', data is selected.(选择数据) When RS= '0', command is selected.(选择寄存器) Serial(串口): This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. (3线串口或者4线串口的时钟信号) |

| | | |
|-------|-------------|--|
| | | If not used, this pin should be connected to IOVCC or GND. (不用时接 IOVCC 或者接地) |
| 11 | WR/A0 (4 线) | Serves as a write signal and writes data at the rising edge. - 4-line system (D/CX): Serves as command or parameter select. <i>Fix to IOVCC level when not in use.</i> (并口的写控制脚或者 4 线串口的寄存器/数据选择, 不用时接 IOVCC) |
| 12 | RD | Serves as a read signal and MCU read data at the rising edge. <i>Fix to IOVCC level when not in use.</i> (并口的读控制脚, 不用时接 IOVCC) |
| 13 | SPI SDI/SDA | Serial input signal. The data is applied on the rising edge of the SCL signal. <i>If not used, fix this pin at IOVCC or GND</i> (串口数据输入信号, 不用时接 IOVCC 或者接地) |
| 14 | SPI SDO | Serial output signal. The data is outputted on the falling edge of the SCL signal. If not used, open this pin (串口数据输出信号, 不用时悬空) |
| 15 | RESET | LCM Reset pin Signal is active low. (屏复位脚, 低电平复位) |
| 16 | GND | Ground (接地脚) |
| 17-24 | DB0-DB7 | Data bus <i>Fix to GND level when not in use</i> (低 8 位数据线, 不用时接地) |
| 25-32 | DB8-DB15 | Data bus <i>Fix to GND level when not in use</i> (高 8 位数据线, 不用时接地) |
| 33 | A | Anode of Backlight (3.0V-3.4V Typical:3.2V) (背光正极供电脚, 电压范围:3.0-3.4V, 典型值:3.2V) |
| 34-36 | K | Cathode of Backlight (背光负极供电脚) |
| 37 | GND | Ground (接地脚) |

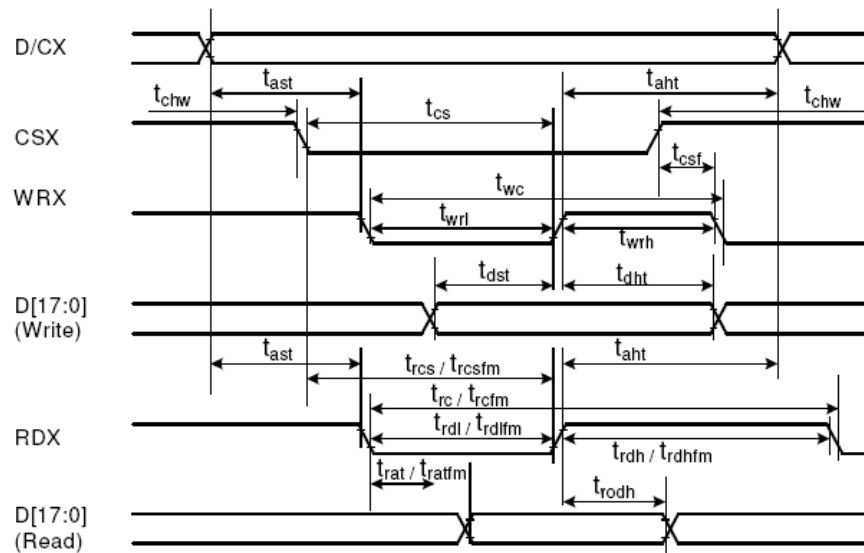
| | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|----|-----|---|---------------------------------------|---------------------|------------------|--------------------------------|--------|------------------|---|---|---|-------------------------------|----------|----------|---|---|---|--------------------------------|--------|---------|---|---|---|-------------------------------|----------|---------|---|---|---|---------------------------------------|---------------------|--|---|---|---|---------------------------------------|---------------------|--|
| | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 38 | IM0 | <div>Select the MCU interface mode (接口选择) IM2 IM1 IM0</div> <table><tr><td>0</td><td>0</td><td>0</td><td>80 MCU 16-bit bus interface II</td><td>D[8:1]</td><td>D[17:10], D[8:1]</td></tr><tr><td>0</td><td>0</td><td>1</td><td>80 MCU 8-bit bus interface II</td><td>D[17:10]</td><td>D[17:10]</td></tr><tr><td>0</td><td>1</td><td>0</td><td>80 MCU 18-bit bus interface II</td><td>D[8:1]</td><td>D[17:0]</td></tr><tr><td>0</td><td>1</td><td>1</td><td>80 MCU 9-bit bus interface II</td><td>D[17:10]</td><td>D[17:9]</td></tr><tr><td>1</td><td>0</td><td>1</td><td>3-wire 9-bit data serial interface II</td><td colspan="2">SDI: In SDO: Out</td></tr><tr><td>1</td><td>1</td><td>0</td><td>4-wire 8-bit data serial interface II</td><td colspan="2">SDI: In SDO: Out</td></tr></table> | 0 | 0 | 0 | 80 MCU 16-bit bus interface II | D[8:1] | D[17:10], D[8:1] | 0 | 0 | 1 | 80 MCU 8-bit bus interface II | D[17:10] | D[17:10] | 0 | 1 | 0 | 80 MCU 18-bit bus interface II | D[8:1] | D[17:0] | 0 | 1 | 1 | 80 MCU 9-bit bus interface II | D[17:10] | D[17:9] | 1 | 0 | 1 | 3-wire 9-bit data serial interface II | SDI: In SDO: Out | | 1 | 1 | 0 | 4-wire 8-bit data serial interface II | SDI: In SDO: Out | |
| 0 | 0 | 0 | 80 MCU 16-bit bus interface II | D[8:1] | D[17:10], D[8:1] | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 0 | 0 | 1 | 80 MCU 8-bit bus interface II | D[17:10] | D[17:10] | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 0 | 1 | 0 | 80 MCU 18-bit bus interface II | D[8:1] | D[17:0] | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 0 | 1 | 1 | 80 MCU 9-bit bus interface II | D[17:10] | D[17:9] | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 1 | 0 | 1 | 3-wire 9-bit data serial interface II | SDI: In SDO: Out | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 1 | 1 | 0 | 4-wire 8-bit data serial interface II | SDI: In SDO: Out | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 39 | IM1 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| 40 | IM2 | <div>NOTE: D[8:1]即低 8 位数据线 DB7-DB0D D[17:10]即高 8 位数据线 DB15-DB8</div> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |

关于供电说明：

IOVCC 和 VCC 连一起，用 2.8V-3.3V 供电；背光 LED 可以单独供电（3.0-3.4 V），也可以和 VCC 共用一组电压（A 为正接 VCC，K 连一起作为负接地）。

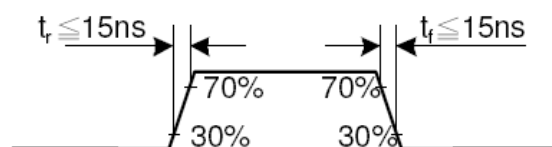
8.2 Timing characteristics.

18.3.2 Display Parallel 18/16/9/8-bit Interface Timing Characteristics(8080- II system)

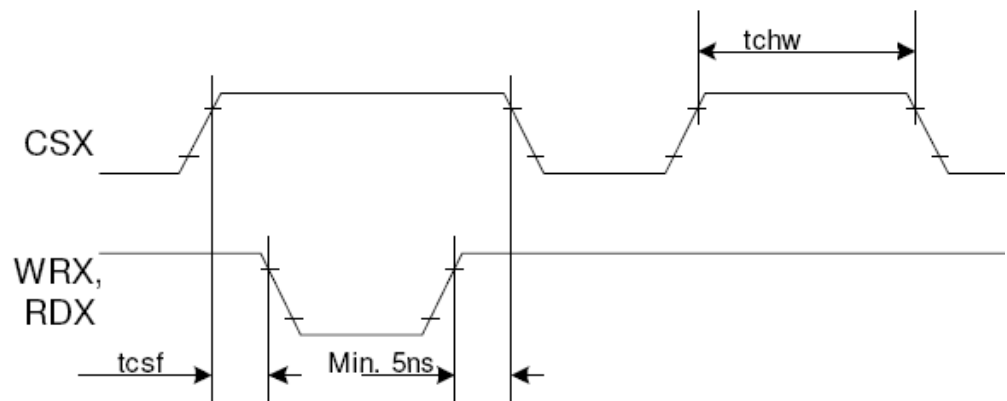


| Signal | Symbol | Parameter | min | max | Unit | Description |
|--|--------|------------------------------------|-----|-----|------|---|
| DCX | tast | Address setup time | 0 | - | ns | |
| | taht | Address hold time (Write/Read) | 0 | - | ns | |
| CSX | tchw | CSX "H" pulse width | 0 | - | ns | |
| | tcs | Chip Select setup time (Write) | 15 | - | ns | |
| | trcs | Chip Select setup time (Read ID) | 45 | - | ns | |
| | trcsfm | Chip Select setup time (Read FM) | 355 | - | ns | |
| WRX | tcsf | Chip Select Wait time (Write/Read) | 10 | - | ns | |
| | twc | Write cycle | 66 | - | ns | |
| | twrh | Write Control pulse H duration | 15 | - | ns | |
| RDX (FM) | twrl | Write Control pulse L duration | 15 | - | ns | |
| | trcfm | Read Cycle (FM) | 450 | - | ns | |
| | trdhfm | Read Control H duration (FM) | 90 | - | ns | |
| RDX (ID) | trdlfm | Read Control L duration (FM) | 355 | - | ns | |
| | trc | Read cycle (ID) | 160 | - | ns | |
| | trdh | Read Control pulse H duration | 90 | - | ns | |
| D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9] | trdl | Read Control pulse L duration | 45 | - | ns | |
| | tdst | Write data setup time | 10 | - | ns | |
| | tdht | Write data hold time | 10 | - | ns | |
| | trat | Read access time | - | 40 | ns | For maximum CL=30pF For minimum CL=8pF |
| | tratfm | Read access time | - | 340 | ns | |
| | trod | Read output disable time | 20 | 80 | ns | |

Note: $T_a = -30$ to 70 °C, $V_{DDI}=1.65V$ to $3.3V$, $V_{CI}=2.5V$ to $3.3V$, $V_{SS}=0V$.

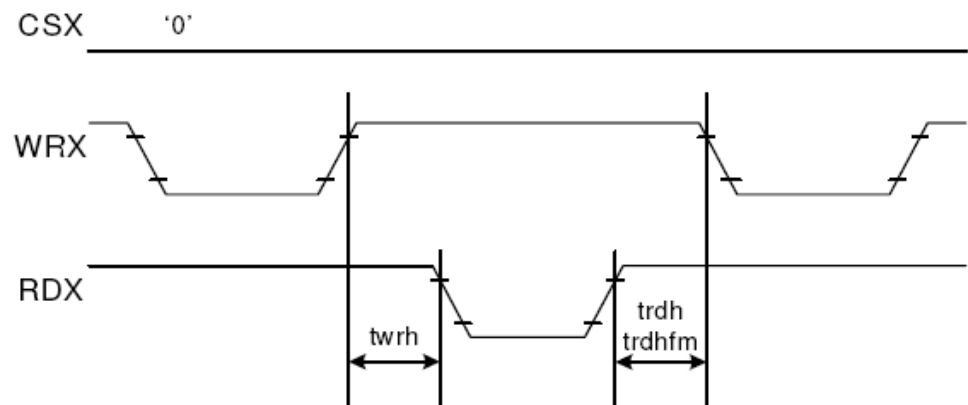


CSX timings :



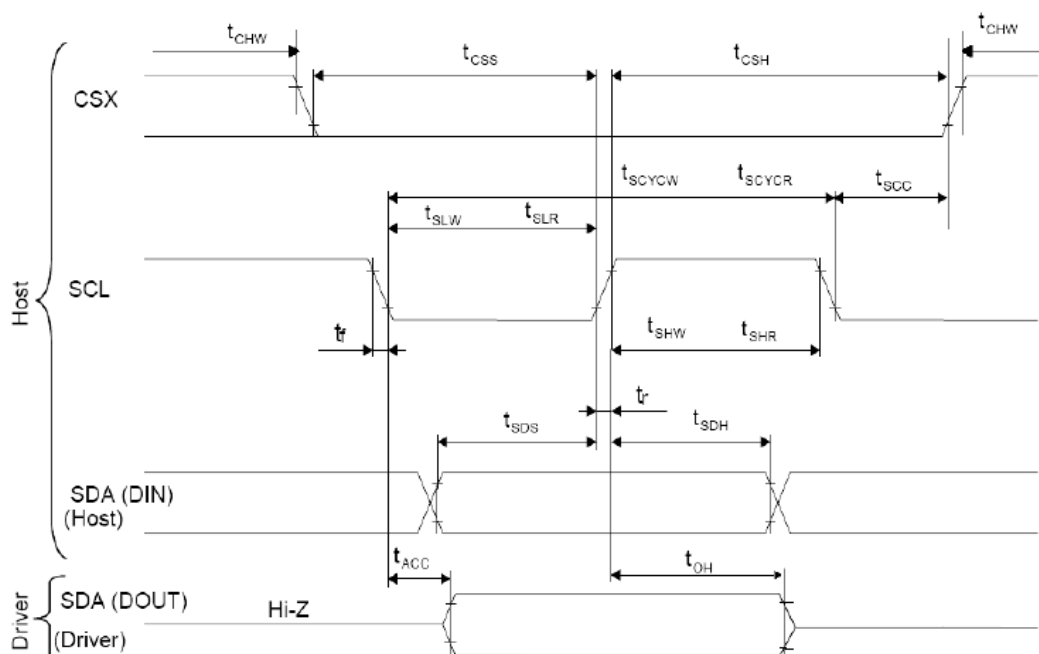
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



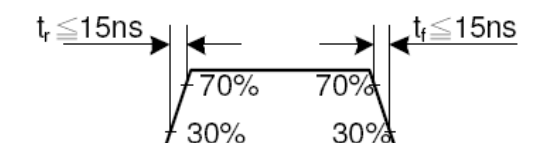
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

18.3.3 Display Serial Interface Timing Characteristics (3-line SPI system)

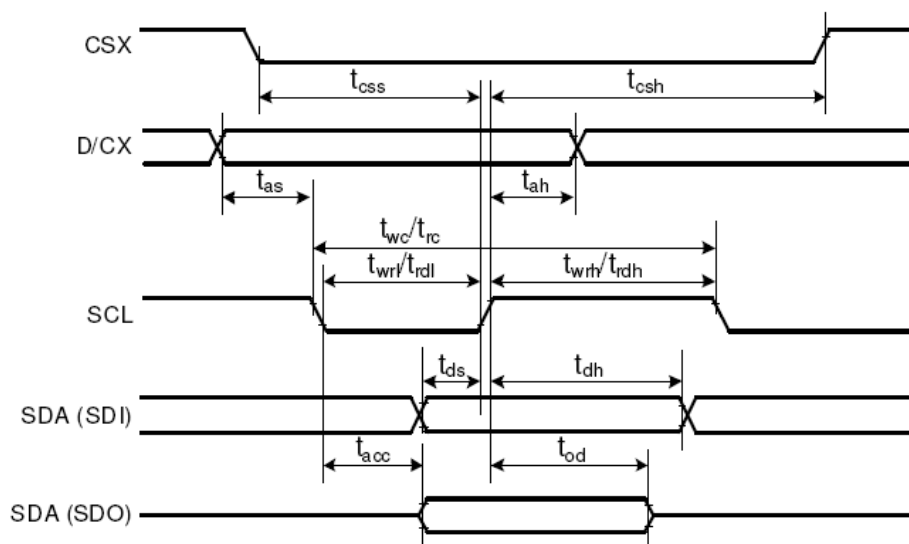


| Signal | Symbol | Parameter | min | max | Unit | Description |
|--------------------|--------|-----------------------------|-----|-----|------|-------------|
| SCL | tscycw | Serial Clock Cycle (Write) | 100 | - | ns | |
| | tshw | SCL "H" Pulse Width (Write) | 40 | - | ns | |
| | tslw | SCL "L" Pulse Width (Write) | 40 | - | ns | |
| | tscycr | Serial Clock Cycle (Read) | 150 | - | ns | |
| | tshr | SCL "H" Pulse Width (Read) | 60 | - | ns | |
| | tslr | SCL "L" Pulse Width (Read) | 60 | - | ns | |
| SDA / SDI (Input) | tsds | Data setup time (Write) | 30 | - | ns | |
| | tsdh | Data hold time (Write) | 30 | - | ns | |
| SDA / SDO (Output) | tacc | Access time (Read) | 10 | - | ns | |
| | toh | Output disable time (Read) | 10 | 50 | ns | |
| CSX | tsc | SCL-CSX | 20 | - | ns | |
| | tch | CSX "H" Pulse Width | 40 | - | ns | |
| | tcs | CSX-SCL Time | 60 | - | ns | |
| | tcs | CSX-SCL Time | 65 | - | ns | |

Note: $T_a = 25^\circ\text{C}$, $V_{DDI}=1.65\text{V to }3.3\text{V}$, $V_{CI}=2.5\text{V to }3.3\text{V}$, $AGND=VSS=0\text{V}$

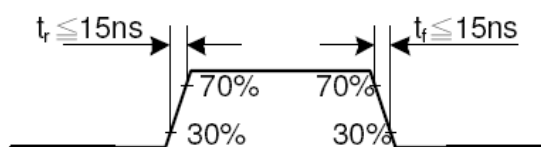


18.3.4 Display Serial Interface Timing Characteristics (4-line SPI system)



| Signal | Symbol | Parameter | min | max | Unit | Description |
|--------------------|--------|-------------------------------|-----|-----|------|---------------------|
| CSX | tcss | Chip select time (Write) | 40 | - | ns | |
| | tcsch | Chip select hold time (Read) | 40 | - | ns | |
| SCL | twc | Serial clock cycle (Write) | 100 | - | ns | |
| | twrh | SCL "H" pulse width (Write) | 40 | - | ns | |
| | twrl | SCL "L" pulse width (Write) | 40 | - | ns | |
| | trc | Serial clock cycle (Read) | 150 | - | ns | |
| | trdh | SCL "H" pulse width (Read) | 60 | - | ns | |
| | trdl | SCL "L" pulse width (Read) | 60 | - | ns | |
| D/CX | tas | D/CX setup time | 10 | - | | |
| | tah | D/CX hold time (Write / Read) | 10 | - | | |
| SDA / SDI (Input) | tds | Data setup time (Write) | 30 | - | ns | |
| | tdh | Data hold time (Write) | 30 | - | ns | |
| SDA / SDO (Output) | tacc | Access time (Read) | 10 | - | ns | For maximum CL=30pF |
| | tod | Output disable time (Read) | 10 | 50 | ns | For minimum CL=8pF |

Note: $T_a = 25^\circ\text{C}$, $V_{DDI}=1.65\text{V to }3.3\text{V}$, $V_{CI}=2.5\text{V to }3.3\text{V}$, $AGND=VSS=0\text{V}$

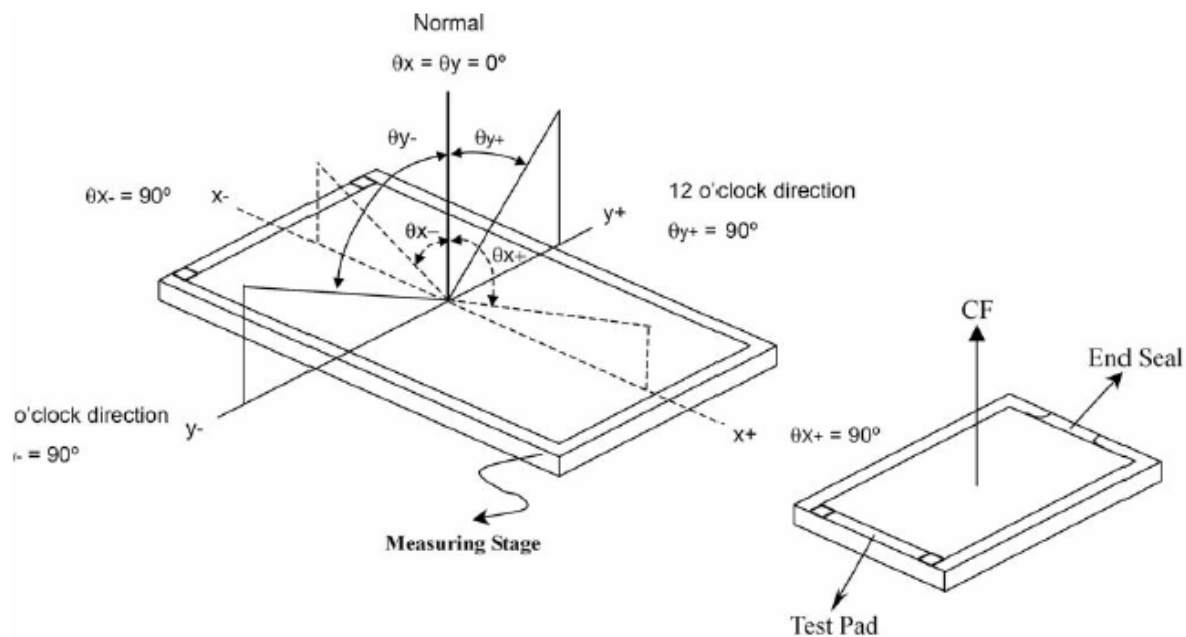


9. Electro-optical Characteristics

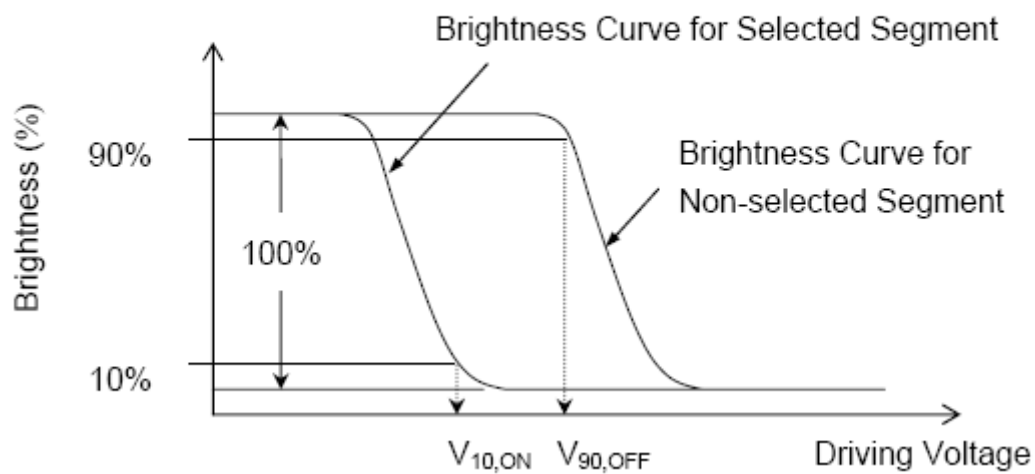
| Item | Symbol | Conditions | Temp | Min. | Typ. | Max. | Unit | Note |
|--|-------------------------|--------------------------|------|----------------------------|------|---------------------------|------|-------|
| Response Time | T_R | $\theta = \phi = 0$ | 25°C | | TBD | TBD | msec | NOTE2 |
| | T_F | | | | TBD | TBD | | |
| Viewing Angle Range | $\phi = 0^\circ (6'')$ | $\phi = 90^\circ (3'')$ | | $\phi = 180^\circ (12'')$ | | $\phi = 270^\circ (9'')$ | | NOTE3 |
| $\theta (25^\circ\text{C}) \text{ CR} \geq 10$ | TBD | TBD | | TBD | | TBD | | NOTE3 |

The above “viewing angle” is the measuring position with the largest contrast ratio. Not for good image quality. Viewing direction for good image quality is 12 O’clock.

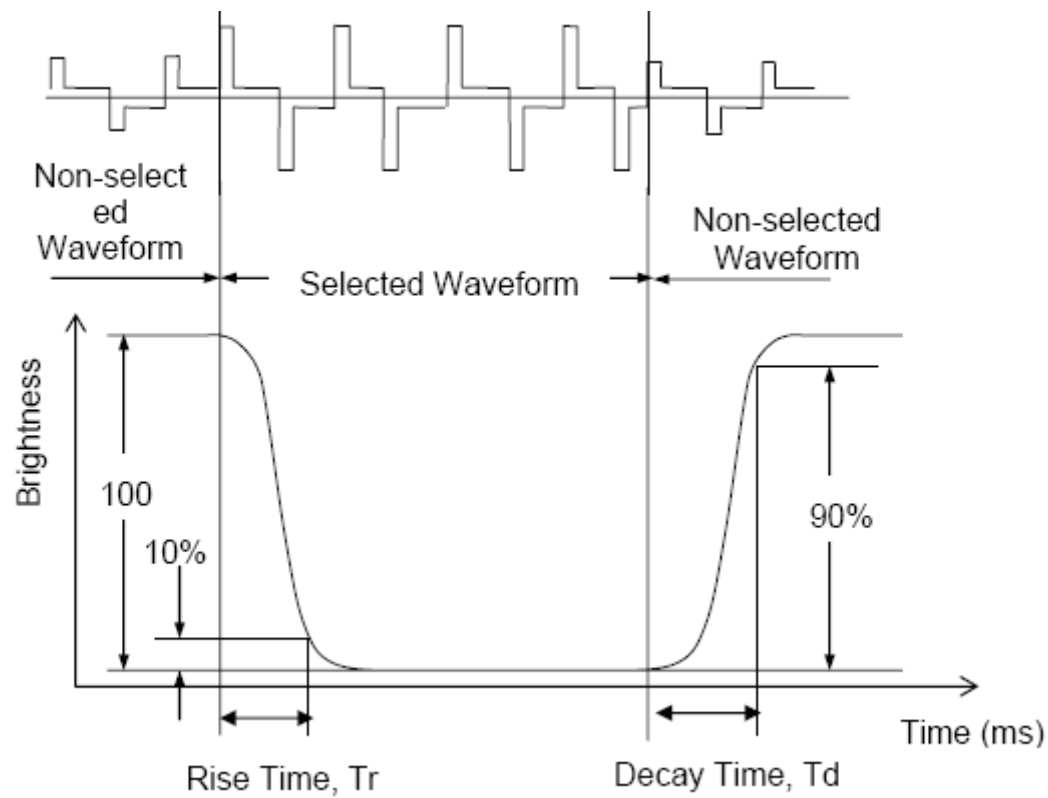
- For panel only
- Electro-Optical Characteristics Test Method



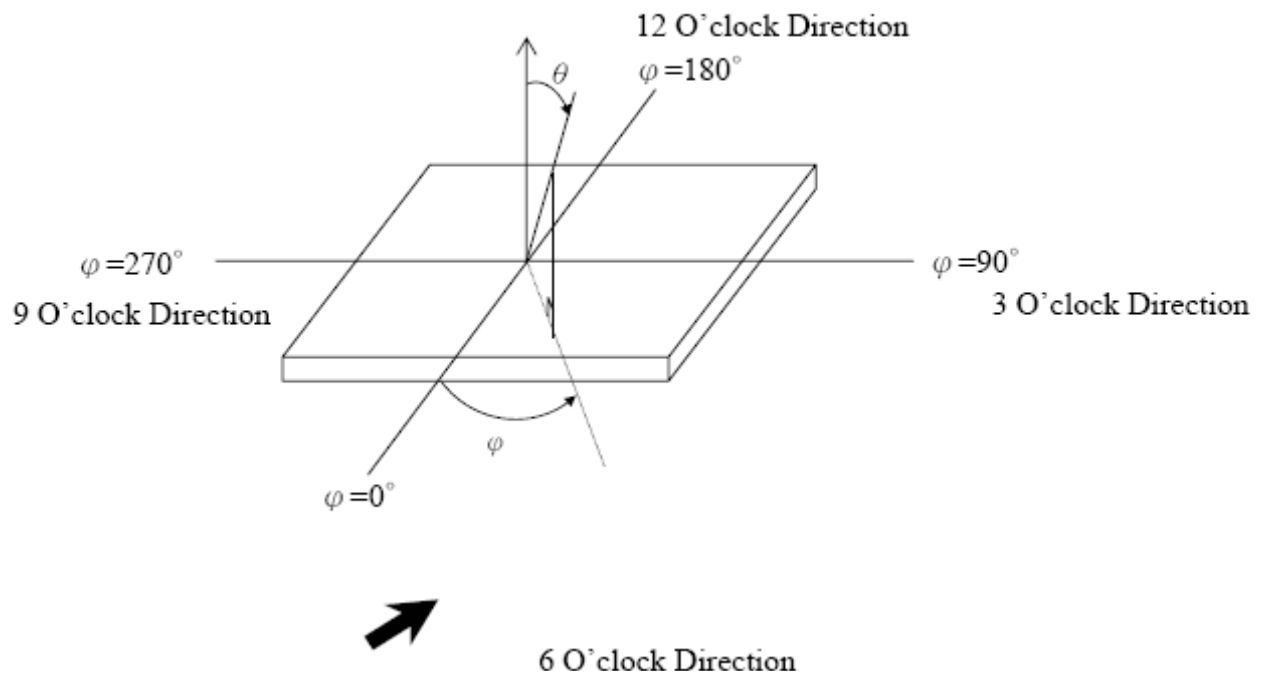
$$V_{op} = (V_{10, ON} + V_{90, OFF})/2$$



.Note2.Definition of Optical Response Time:

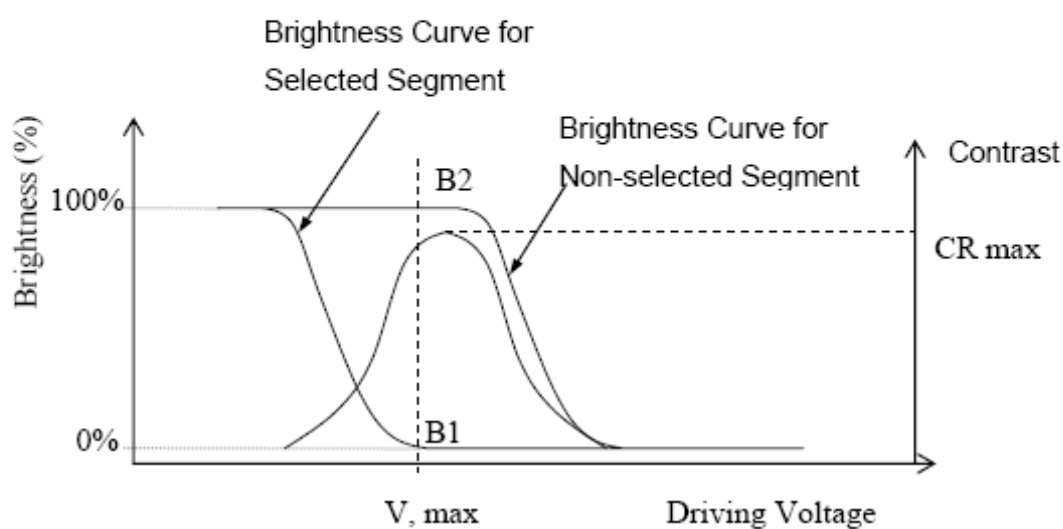


.Note3.Definition of Viewing Angle θ and ϕ :



Note4.Definition of Contrast ratio (CR):

$$CR = \frac{\text{Brightness of Non-selected Segment (B2)}}{\text{Brightness of Selected Segment (B1)}}$$



10. Reliability

10.1Mtbf

The LCD module shall be designed to meet a minimum MTBF value of 50000 hours with normal

10.2Test condition

| NO. | ITEM | CONDITION | CRITERION |
|-----|--|---|--|
| 1 | High Temperature Non-Operating Test | 80°C*240Hrs | <ul style="list-style-type: none"> No Defect Of Operational Function In Room Temperature Are Allowable IDD of LCM in Pre-and Post-Test Should Follow Specification |
| 2 | Low Temperature Non-Operating Test | -30°C*240Hrs | |
| 3 | High Temperature/Humidity Non Operating Test | 60°C*90%RH*240Hrs | |
| 4 | High Temperature Operating Test | 70°C*240Hrs | |
| 5 | Low Temperature Operating Test | -20°C*240Hrs | |
| 6 | Thermal Shock Test | -20 °C (30Min) ↔ 70 °C (30Min) *10CYCLES | |

Notes:

- Judgments should be made after exposure in room temperature for two hours.
- The distill water is used for the high temperature/humidity test.
- The sample above is individually for every reliability tests condition.

11.Inspection standards

1.AQL(Acceptable Quality Level

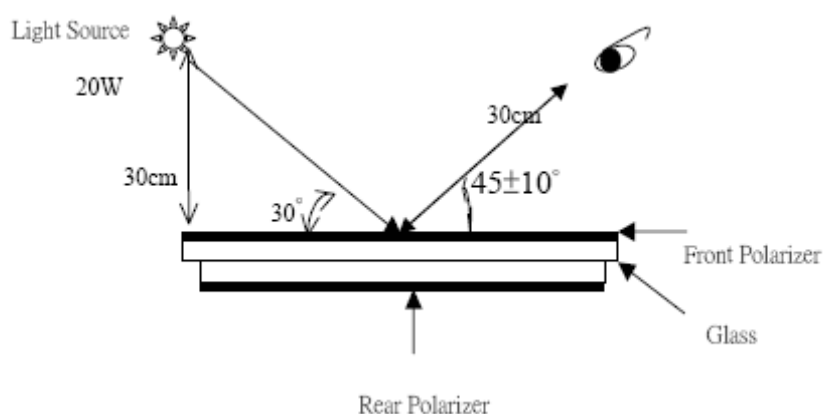
AQL of major and minor defect.

| | MAJOR DEFECT | MINOR DEFECT |
|-----|--------------|--------------|
| AQL | 0.65 | 1.5 |

2. Basic conditions for inspection

The LCM face to us, in normal environment, the lux is 1000 ± 200 . (Darkroom's lux: 100 ± 50), About an angle of incidence 30, a distance of 30 cm with an angle of 45 degree to check the products without uncovering the film!


(As shown below)

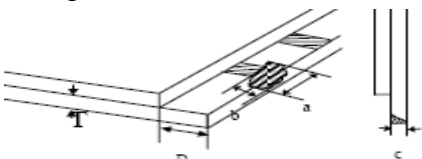
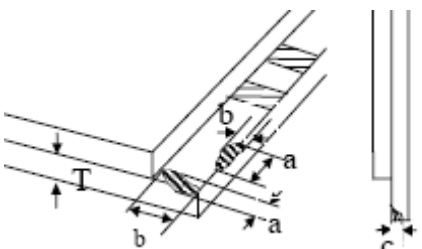
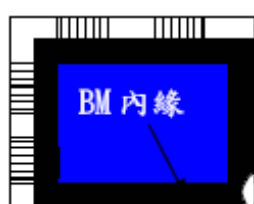


3.Inspection item and criteria

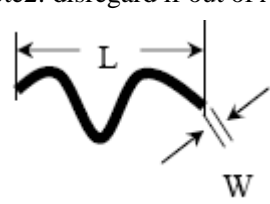
3.1 Visual inspection criterion in immobility

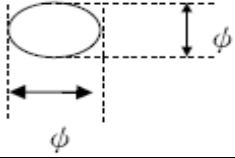
3.1.1Glass defect

| NO | Defect item | Criteria | Remark |
|----|--|--|---|
| 1 | Dimension Unconformity (Major defect) | By Engineering Drawing | |
| 2 | Cracks (Major defect) | 1. Linear cracks panel 2. Nonlinear crack contrast by limited sample 【Reject】 |  |
| 3 | Glass extrude the conductive area (minor defect) | a: disregards and no influence assemblage. 1) $b \leq 1/3$ Pin width (non bonding | A: Length, b: Width |

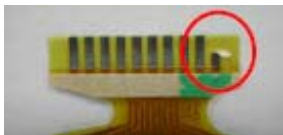
| | | | |
|---|--|--|---|
| | | area) 2)bonding area $\leq 0.5\text{mm}$ 【Accept】 | |
| 4 | Pin-side ,conductive area damaged (minor defect) | (a c: disregards) $b \leq 1/3$ of effective length for bonding electrode 【Accept】 | a: length, b: Width, c: Thickness  |
| 5 | Pin-side,non-conductive area damaged (minor defect) | 1)Damage area don't touch the ITO (Including contraposition mark, except scribing mark) 【Accept】 2) $C < T$ $b \leq BM1/3$ of width 【Accept】 3) $c = T$ b not touch the seal glue 【Accept】 4)a disregards | a: Length, b: Width c: Thickness  |
| 6 | Non-pin-side damage (minor defect) | $c < T$ 1)b exceeds $1/3 BM$ 【Reject】 $c = T$ b not touch the seal glue 【Reject】 | c: Thickness b: width of  damage |

3.1.2LCD appearance defect(View area)

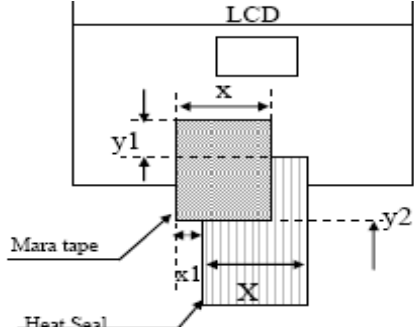
| NO | Defect item | Criteria | | Remark |
|----|---|--|-----------|---|
| 1 | Fiber、 glass cratch、 polarizer scratch/folded (minor defect) | Specification | Allowable | note1:L: Length, W: Width note2: disregard if out of AA  |
| | | $W \leq 0.03\text{mm}$ | disregard | |
| | | $0.03\text{mm} < W \leq 0.05\text{mm};$ $L \leq 3.0\text{mm}$ | 2 | |
| | | $0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$ | 1 | |
| | | $W > 0.1\text{mm}; L > 3.0\text{mm}$ | 0 | |

| | | | | |
|---|---|---|-----------|---|
| 2 | Polarizer bubble、 concave and convex (minor defect) | $\phi \leq 0.2\text{mm}$ | disregard | note1: $\phi = (L+W)/2$, L:Length, W :Width note2:disregard if out of AA |
| | | $0.2\text{mm} < \phi \leq 0.3\text{mm}$ | 2 | |
| | | $0.3\text{mm} < \phi \leq 0.5\text{mm}$ | 1 | |
| | | $0.5\text{mm} < \phi$ | 0 | |
| 3 | Black dots、dirty dots、 impurities、eye winker (minor defect) | $\phi \leq 0.15\text{mm}$ | disregard | note2:disregard if out of AA  |
| | | $0.15\text{mm} < \phi \leq 0.25\text{mm}$ | 2 | |
| | | $0.25\text{mm} < \phi \leq 0.3\text{mm}$ | 1 | |
| | | $0.3\text{mm} < \phi$ | 0 | |
| 4 | Polarizer prick (minor defect) | $\phi \leq 0.1\text{mm}$ | disregard | note1: $\phi = (L+W)/2$, L=Length, W=Width note2:the distance between two dots>5mm |
| | | $0.1\text{mm} < \phi \leq 0.25\text{mm}$ | 3 | |
| | | $\phi > 0.25\text{mm}$ | 0 | |

3.1.3FPC

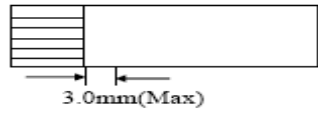
| NO | Defect item | Criteria | | Remark |
|----|--|-------------------------------------|-----------|---|
| 1 | Copper screen peel (minor defect) | Copper screen peel 【Reject】 | |  |
| 2 | No release tape or peel | No release tape or peel 【Reject】 | | |
| 3 | Dirty dot and impurity of FPC for customer using side (minor defect) | Specification | Allowable | Note1: Cannot have stride ITO impurities |
| | | $\phi \leq 0.25\text{mm}$ | 2 | |
| | | $\phi > 0.25$ | 0 | |

3.1.4Black tape & Mara tape

| NO | Defect item | Criteria | Remark |
|----|---|--|--|
| 1 | FPC or H/S black tape (minor defect) | 1. shift spec: 1) glue to the polarize 【Reject】 2) IC bare 【Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【Reject】 2) IC bare 【Reject】 |  |

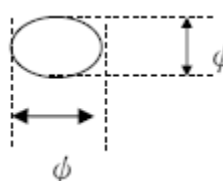
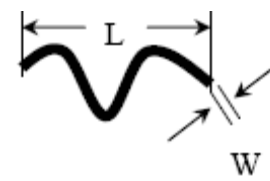
| | | | |
|---|---|--|--|
| 2 | No black tape (major defect) | No black tape 【Reject】 | |
| 3 | Tape position mistake (minor defect) | Not by engineering drawing | |
| 4 | Mara tape defect (minor defect) | Peel before pulling the protecting film 【Reject】 | |

3.1.5 Silicon and Taffy glue

| NO | Defect item | Criteria | Remark |
|----|--|---|---|
| 1 | Quantity of silicon (major defect) | Uncover the ITO and circuit area 【Reject】 | note: compared by engineering |
| 2 | Taffy glue (major defect) | 1.Uncover the reveal copper area【Reject】 2.Cover layer 0.3mm(Min)~3.0mm(Max) 【Reject】 | note: if customer has special requirement, refer to the technical document  |
| 3 | Depth of glue covering (major defect) | Depth of glue covering overtop front Polarizer 【Reject】 | Except of the special requirement |

3.2Electrical criteria

| NO | Defect item | Criteria | Remark |
|----|--|--------------------------------------|-------------------|
| 1 | No display (major defect) | No display 【Reject】 | |
| 2 | Missing line (major defect) | Missing line 【Reject】 | |
| 3 | Seg-com light and dark (major defect) | Seg-com light and dark 【Reject】 | ND filter 2% test |
| 4 | No display in immobility (major defect) | No display in immobility 【Reject】 | |
| 5 | Flicker of Pattern (major defect) | Flicker of Pattern 【Reject】 | |
| 6 | Mura (major defect) | ND filter 2%test | |
| 7 | Over current | Over current | |

| | | | | |
|----|---|---|-----------|---|
| | (major defect) | 【Reject】 | | |
| 8 | Voltage out of specification (major defect) | Voltage out of specification 【Reject】 | | |
| 9 | Pattern blur, error code (major defect) | Pattern blur, error code 【Reject】 | | |
| 10 | Dark light, Flicker (major defect) | Dark light, Flicker 【Reject】 | | |
| 11 | Black/white dots 、 Dirty dots、 eye winker (major defect) | Specification | Allowable | Note1:disregard if out of AA  |
| | | $\phi \leq 0.15\text{mm}$ | disregard | |
| | | $0.15\text{mm} < \phi \leq 0.25\text{mm}$ | 2 | |
| | | $0.25\text{mm} < \phi \leq 0.3\text{mm}$ | 1 | |
| | | $0.3\text{mm} < \phi$ | 0 | |
| 12 | Fiber、glass crutch、Polarizer scratch/folded (major defect) | $W \leq 0.03\text{mm}$ | disregard | Note1:L: Length, W: Width Note2: disregard if out of AA  |
| | | $0.03\text{mm} < W \leq 0.05\text{mm}$ $L \leq 3.0\text{mm}$ | 2 | |
| | | $0.05\text{mm} < W \leq 0.1\text{mm}$ $L \leq 3.0\text{mm}$ | 1 | |
| | | $W > 0.1\text{mm}; L > 3.0\text{mm}$ | 0 | |
| | | | | |

12.Precautions for using LCD modules.

12.1 Safety

- (1)Do not swallow any liquid crystal ,even if there is no proof that liquid crystal is poisonous.
- (2)If the LCD panel breaks, be careful not to get liquid crystal to touch your skin.
- (3)If skin is exposed to liquid crystal, wash the area thoroughly with alcohol or soap.

12.2Storage Conditions

- (4)Store the panel or module in a dark place where the temperature is $23 \pm 5^{\circ}\text{C}$ and the humidity is below $45 \pm 20\% \text{RH}$.
- (5)Store in anti-static electricity container.

-
- (6)Store in clean environment, free from dust, active gas, and solvent.
(7)Do not place the module near organics solvents or corrosive gases.
(8))Do not crush, shake, or jolt the module.

12.3Handling Precautions

- (9)Avoid static electricity, which can damage the CMOS LSI.
(10)The polarizing plate of the display is very fragile, please handle if very carefully.
(11)Do not give external shock.
(12)Do not apply excessive force on the surface.
(13)Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
(14)Do not use ketonics solvent & Aromatic solvent, use with a soft cloth soaked with a cleaning naphtha solvent.
(15)Do not operate it above the absolute maximum rating.
(16)Do not remove the panel or frame from the module.

12.4Warranty

The period is within twelve months since the date of shipping out under normal using and storage conditions.

13.Revision history

| Version | Revise record | Date |
|---------|------------------|------------|
| v0.0 | Original version | 2014-02-16 |
| V0.3 | Changed LCD | 2014-05-16 |